

# UNISONIC TECHNOLOGIES CO., LTD

05N65-MH Preliminary Power MOSFET

# 0.5A, 650V N-CHANNEL POWER MOSFET

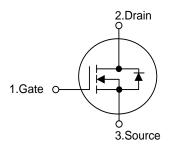
### **■ DESCRIPTION**

The UTC **05N65-MH** is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

### **■ FEATURES**

- \*  $R_{DS(ON)} \le 17~\Omega$  @  $V_{GS} = 10V$ ,  $I_D = 0.25A$
- \* Fast switching capability
- \* Avalanche energy specified
- \* Improved dv/dt capability, high ruggedness

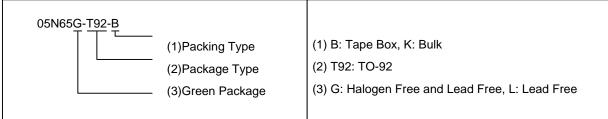
#### ■ SYMBOL



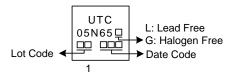


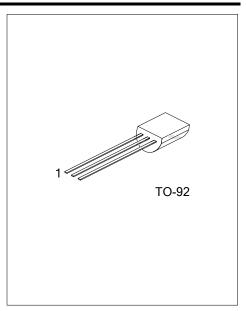
Ordering Number		Doolsone	Pin	Assignr	Doolsing		
Lead Free	Halogen Free	Package	1	2	3	Packing	
05N65L-T92-B	05N65G-T92-B	TO-92	G	D	S	Tape Box	
05N65L-T92-K	05N65G-T92-K	TO-92	G	D	S	Bulk	

Note: Pin Assignment: G: Gate D: Drain S: Source



## **■ MARKING**





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# ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub> = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	650	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Drain Current	Continuous	I <sub>D</sub>	0.5	Α
	Pulsed (Note 2)	I <sub>DM</sub>	1.0	Α
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	10	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	3.2	V/ns
Power Dissipation		$P_{D}$	1.4	W
Junction Temperature		$T_J$	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ <b>+</b> 150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 30mH,  $I_{AS}$  = 0.8A,  $V_{DD}$  = 50V,  $R_{G}$ = 25 $\Omega$  , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 4.  $I_{SD} \le 0.5A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_{J} = 25^{\circ}C$

### **■ THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	$\theta_{JA}$	160	°C/W	
Junction to Case	$\theta_{JC}$	88 (Note)	°C/W	

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

## ■ **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> =25°C, unless otherwise specified)

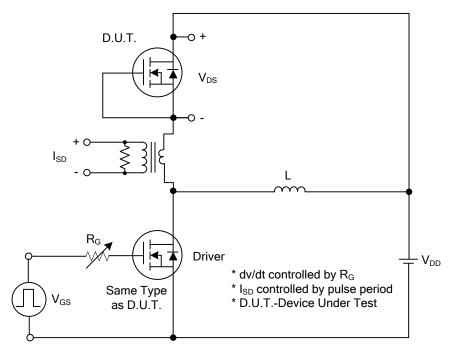
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS									
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	$V_{GS}=0V, I_{D}=250\mu A$	650			V		
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V			10	μΑ		
Gate-Source Leakage Current	Forward		V <sub>GS</sub> =30V, V <sub>DS</sub> =0V			100	nA		
	Reverse	$I_{GSS}$	$V_{GS}$ =-30V, $V_{DS}$ =0V			-100	nA		
ON CHARACTERISTICS									
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2.0		4.0	V		
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.25A			17	Ω		
DYNAMIC CHARACTERISTICS	3								
Input Capacitance		$C_{ISS}$			70		pF		
Output Capacitance		Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		13		pF		
Reverse Transfer Capacitance		$C_{RSS}$			1.5		pF		
SWITCHING CHARACTERISTIC	cs								
Total Gate Charge (Note 1)		$Q_G$	V 520V V 40V I 0.5A		7		nC		
Gate to Source Charge		$Q_GS$	$V_{DS}$ =520V, $V_{GS}$ =10V, $I_{D}$ =0.5A, $I_{G}$ =1mA (Note 1, 2)		3.5		nC		
Gate to Drain Charge		$Q_GD$	IG=TITIA (NOTE 1, 2)		0.9		nC		
Turn-ON Delay Time (Note 1)		t <sub>D (ON)</sub>			3.2		ns		
Rise Time		t <sub>R</sub>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A,		15		ns		
Turn-OFF Delay Time		t <sub>D (OFF)</sub>	R <sub>G</sub> =25Ω (Note 1, 2)		11		ns		
Fall-Time		$t_{F}$			36		ns		
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS									
Maximum Body-Diode Continuous Current		I <sub>S</sub>				0.5	Α		
Maximum Body-Diode Pulsed Current (Note 1)		I <sub>SM</sub>				1.0	Α		
Drain-Source Diode Forward Voltage (Note 1)		$V_{SD}$	I <sub>S</sub> =0.5A, V <sub>GS</sub> =0V			1.4	V		
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>S</sub> =0.5A, V <sub>GS</sub> =0V		130		ns		
Body Diode Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		1		μC		

Notes: 1. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%

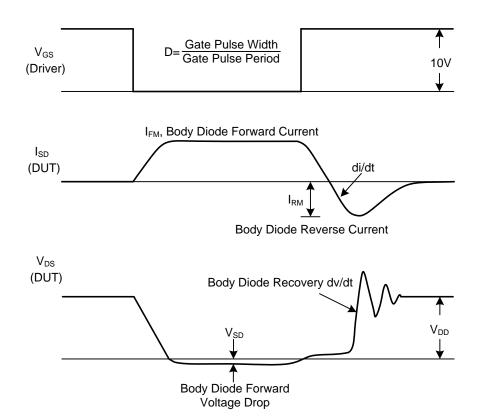
2. Essentially independent of operating temperature.



## ■ TEST CIRCUITS AND WAVEFORMS

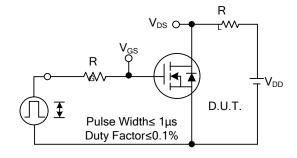


Peak Diode Recovery dv/dt Test Circuit

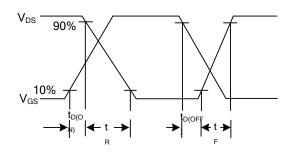


Peak Diode Recovery dv/dt Waveforms

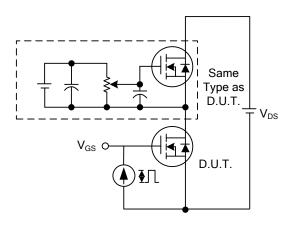
## ■ TEST CIRCUITS AND WAVEFORMS



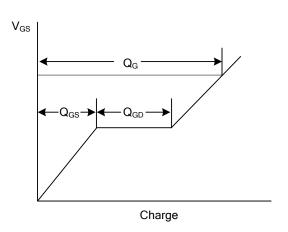
Switching Test Circuit



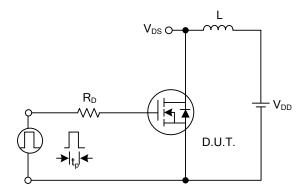
**Switching Waveforms** 



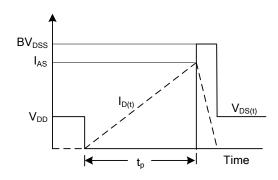
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

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